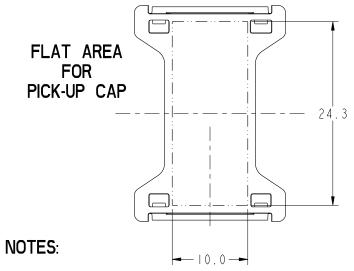


PRODUCT NUMBER	SOLDER BALL
10054783-001	SnPb
10054783-001LF	SnAgCu LEADFREE SEE NOTE 7 8



-PLUG ASSY -PCB P/N 10054783 DIM. "A" REF. MATED HEIGHT AFTER REFLOW SEE NOTE 3. -RECPT. ASSY. (SEE TABLE)

END VIEW OF MATED CONNECTORS

RECPT. ASSY. P/N DIM. "A" 30 55740 35 10026010 40 55741

Α

(I) MAT'L:

HOUSING: LCP

CONTACT: COPPER ALLOY

PLATING (CONTACT): Au OVER Ni.

UL RATING: 94 V-O

SOLDER BALL: (SEE TABLE) EUTECTIC SnPb OR LEADFREE 95.5 Sn/4Aq/0.5Cu

(2) SOLDER BALLS WILL NOT BE PERFECT SHPERICAL SHAPE DUE TO REFLOW ATTACHMENT.

(3) MATED HEIGHT EFFECTED BY CUSTOMERS' PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE & SOLDER PASTE.

(4) CONTACTS IN ROWS A,C,E,G,J,K,M,P,R AND T ARE SINGLE BEAM CONTACTS, TYPICALLY USED AS GROUND PINS. (NOTE: CONTACTS IN ROWS J & K ARE TIED TOGETHER [COMMONED])

mat 'I	code		SEE	NOT	ΕΙ	tolerances unless otherwise specified						STOM	1ER	FG)								
Itr	ecn	no.	dr	do	te			0.X:	(±0.3		COPY					4		www.fciconnect.c				
C	-		-			linear	$0.XX \pm 0.$		±0.1	=0.10		projection		title GIG-Array								
							$0.XXX \pm 0.050$						250	25mm PLUG ASSY. 200 SIG. PO						0.0		
				angles	0° ±2°			$ \Psi \cup$			2311	ZJIIIII FLUU AJJI. ZUU JIU. FU										
					dr engr chr				2/05	MM			product family GIG-Array code									
									3/22/05 3/22/05		scale		size	dwg	dwg no				2   3 sheet			
														10054783				3				
						appd	D. H.	ARPER	3/2	2/05		1:1		A		0 0	J <del>1</del>	10	J		4	
she	sheet revi		ion																			
ind	index s																					
		Pı	o/E							3			cag	e code	, 2	252	6		4			

 $1 \mid 2$ 

PDM: Rev:C

STATUS Released

22526

NOT TOOLED

Printed: Jul 14, 2006

В

This accument is the property of and embodies CONFIDENTIAL and PROPRIETARY information of FCI. No port of the information shown on this accument may be used in any way or disclosed to others without the written consent of FCI. Copyright FCI.

В

REV E - 2006-04-18

4

Α

- (5) CONTACTS IN ROWS B,D,F,H,L,N,Q AND S ARE DUAL BEAM CONTACTS, TYPICALLY USED AS SIGNAL PINS.
- 6 SPECIFIED POSITIONAL TOLERANCE DEFINES PAD TO PAD LOCATION WITHIN LAND PATTERN. POSITIONAL TOLERANCE OF LAND PATTERN TO FUDICIAL MARKS OR PCB DATUMS SHALL BE DEFINED BY CUSTOMER. FOR RECOMMENDED PRODUCT APPLICATION AND PCB DESIGN DETAILS, SEE DOC. NO. GS-20-016.
- 7) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEADFREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE, LEADFREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS, REFERENCE FCI APPLICATION SPECIFICATION.
- (8) THIS PRODUCT MEETS THE EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN HTE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION.

**ご**》

Α

This document is the property of and embodies CONFIDENTIAL and PROPRIETARY information of FCI. No part of the information shown on this document may be used in any way or disclosed to others without the written consent of FCI. Capyright FCI.

mat'l code		SEE	1	tolerances unless otherwise specified						STOM	ER	<b>FG</b> j									
ltr	ecn	n no. dr date				0.X ±0.3					COPY		www.fciconnect.com								
С	-			- lin		0.XX ±0.10			projection			title		(	3 I G - 1	Arra					
							$0.XXX \pm 0.050$			4	7 ~	1 25mm	m Di	GIG-Array					Λ¢		
					c	angles	0° ±2°			W 7			25mm PLUG ASSY. 200 SIG. POS.								
						dr	T. BRUNGARD		3/22/	2/05	MM			produ	ct fam	ily	GΙ	G - A r	ray	code	
						engr	D. HARPER D. HARPER		3/22/05 3/22/05		scale		si	size	-	no			3	213	
						chr								Ι _Λ		$\cap \cap$	5/	78		she	et
					appd D. HARPER 3/2		2/05		1:1		A		0 0	34103			5				
sheet		revisi	on																		
index sh		sheet																			

3 l

PDM: Rev:C

Pro/E

STATUS Released

Printed: Jul 14, 2006

22526

В

1 2

В

REV E - 2006-04-18